

Design of 1R/1W 8T SRAM Cell

ECE-611 (Memory Design and Testing)

Group - 1

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Given specification :

- $V_{min}(\text{read port}) = 0.81V$
- $V_{min}(\text{write port}) = 1.08V$ when mux 16
- $V_{min}(\text{write port}) = 0.81V$ when mux 1 with WL Boost
 $I_{cell} = 100\mu A$ at wc, 1.08V

Understanding:

- ❖ Sizing of write port is determined on the basis of SNM and write functionality.
- ❖ I_{cell} needs to be 100uA at worst PVT condition, i.e. SS, Low voltage 1.08V, 125C.
- ❖ I_{cell} determines the sizing of NMOS stack at the read ports, $I_{cell} \uparrow$, Read speed \uparrow .

Challenges



- Eldo commands for various FOM simulations to be done for SNM, Icell, Write Time, Write Margin etc.
- Six sigma qualification of SNM, such that sizing should ensure that the lowest and worst PVT has required 6-7 sigma margin only.
- Obtaining minimum area bitcell layout to meet design requirements efficiently.
- Designing array structure by flipping and sharing bitcell and routing various shared signals with different metal layers across the array in the minimum area possible.
- Overcoming challenges in creating layouts that meet Design Rule Checks (DRC) and Layout versus Schematic (LVS) criteria, ensuring cleanliness and compliance with design standards.
- We encountered challenge in achieving sigma qualification for bitcell figure of merits (FOMs).

Design of 1R/1W 8T SRAM Cell

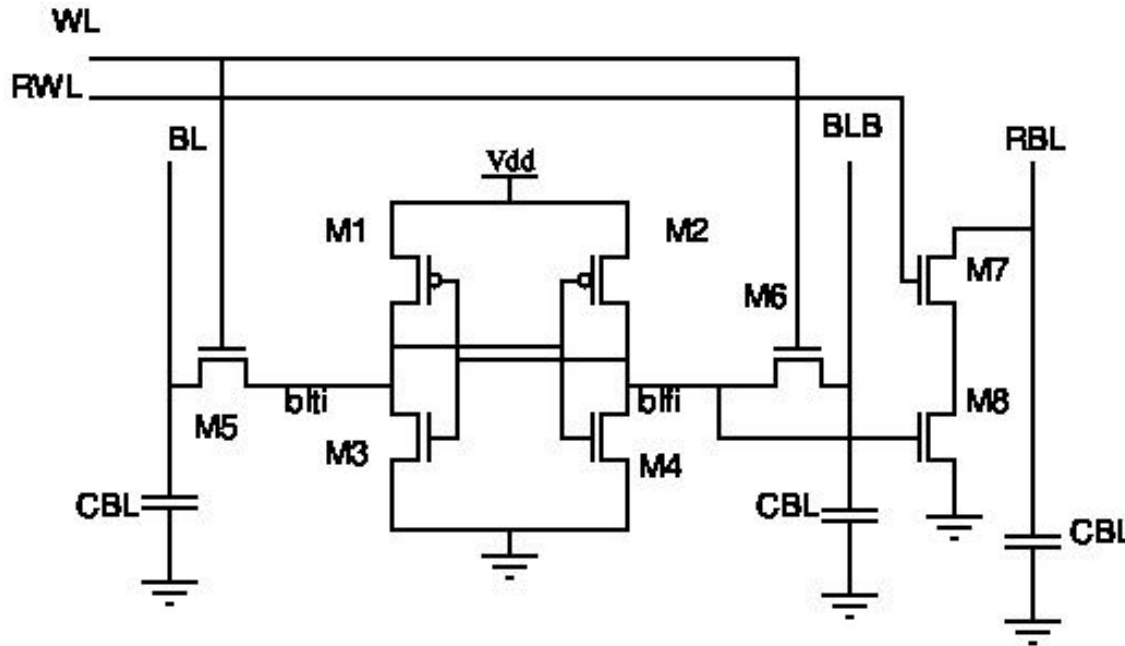


Fig 1: Schematic of 8T SRAM cell

KEY POINTS:

- The Read and Write ports are decoupled.
- NMOS stack in Read Port is sized according to I_{cell} .
- More stable and faster cell, suitable for LV operations as retention voltage gets reduced.
- Additionally the cell can also use ports as 1RW/1R.
- I_{Pon} is the additional FOM that needs to be taken care to avoid accidental read by SA.

Transistor	Sizings (W/L)		Constraint
	Initial	Final	
<i>Read Port (M7, M8)</i>	0.220/0.085	0.200/0.08	I _{cell} =100uA
<i>Pull Up (M1,M2)</i>	0.135/0.085	0.135/0.085	Minimum sized device
<i>Pass Gate (M5,M6)</i>	0.175/0.085	0.170/0.085	Read SNM 6-Sigma Write Functionality
<i>Pull Down (M3,M4)</i>	0.260/0.085	0.210/0.085	Read SNM 6-Sigma Write Functionality

Verification Plan, Stimuli and PVT conditions



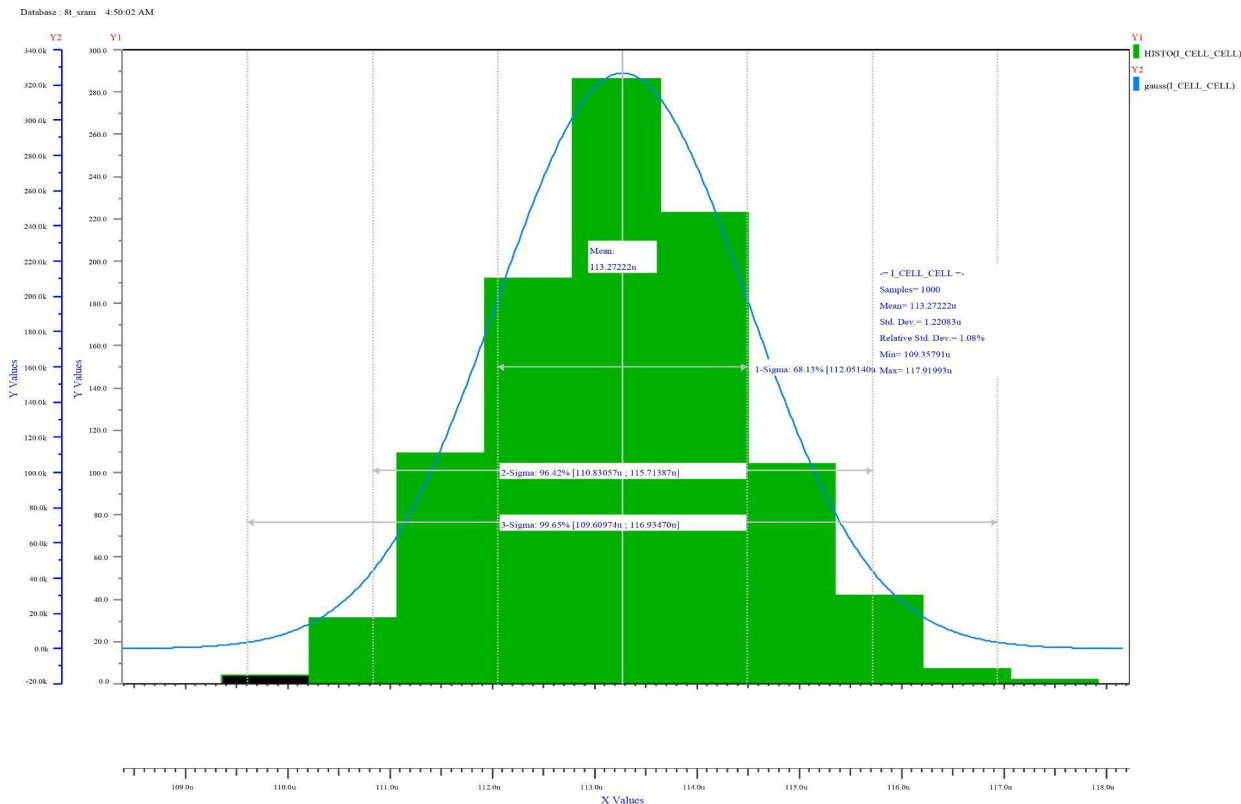
FOMs		PROCESS CORNER	STIMULI	PRE SIMULATION VALUE	POST SIMULATION VALUE
Read SNM		FS, 1.08V, 125C	BL, WL = High	—	132.64 mV
		FS, 0.81V, 125C		—	110.16 mV
Cell Current		SS, 1.08V, 125C	RWL, WL = High, Q_Bar = 1	151.78 μ A	123.88 μ A
		SS, 0.81V, 125C		51.75 μ A	97.27 μ A
Write Margins	WL Write Margin	SF, 0.81V, 125C	BLB=High, BL=Low, WL=High	0.607 V	0.570 V
		SF, 0.81V, -40C		0.61 V	0.565 V
	BL Write Margin	SF, 0.81V, 125C		—	0.530 V
		SF, 0.81V, -40C		—	0.567 V

Verification Plan, Stimuli and PVT conditions



FOMs	PROCESS CORNER	STIMULI	PRE SIMULATION VALUE	POST SIMULATION VALUE
Write Time	SF, 0.81V, -40C	BLB=High, BL=Low, WL=High	6.24 ns	12.194 ns
	TT, 0.81V, -40C		3.118 ns	10.23 ns
Leakage	FF, 1.08V, 125C	All devices are in OFF state. WL, RWL =0	77.35 pA	430 pA
	FF, 0.81V, 25C		29.67 pA	81 pA
I_{Partial}(ON) (Additional FOM for 8T)	FS, 1.08V, 125C	RWL = High, Q = 1 Q_Bar = 0	—	2.4008 μ A

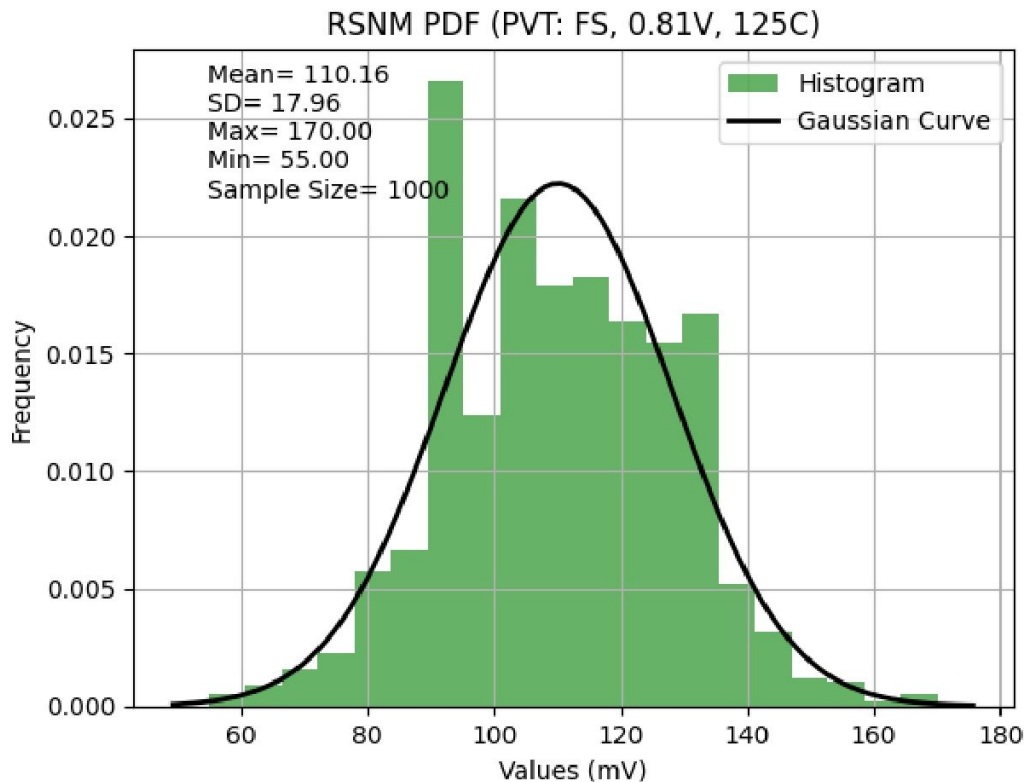
PDF for Icell (Post Layout)



**Icell @SS, 1.08V, 125C
Six Sigma Qualified**

Mean (μ) = 113.27 μ A
SD (σ) = 1.221

$\mu - 6*(\sigma) =$
105.95 μ A > 100 μ A

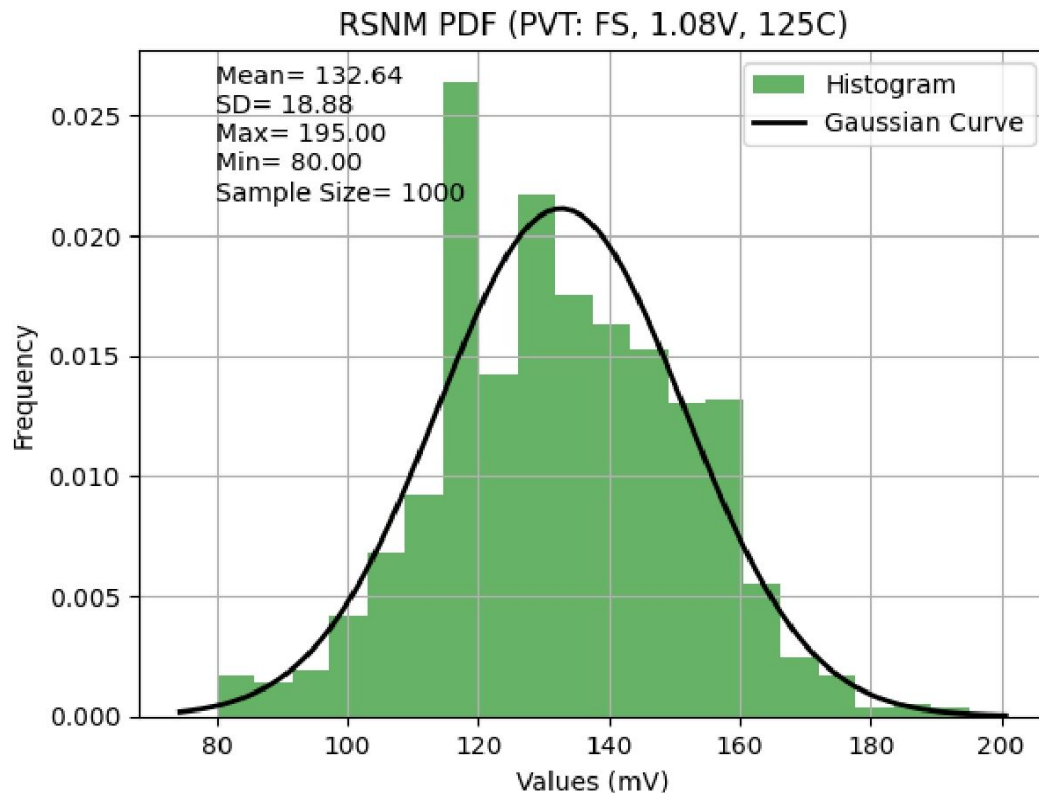


SNM @FS, 0.81V, 125C
Six Sigma Qualified

Mean (μ) = 110.16 mV
SD (σ) = 17.96

$\mu/(\sigma) = 6.1336$

PDF for SNM (Post Layout)



SNM @FS, 1.08V, 125C
Six Sigma Qualified

Mean (μ) = 132.64 mV

SD (σ) = 18.88

$\mu/(\sigma) = 7.025$

I_Partial_(ON)



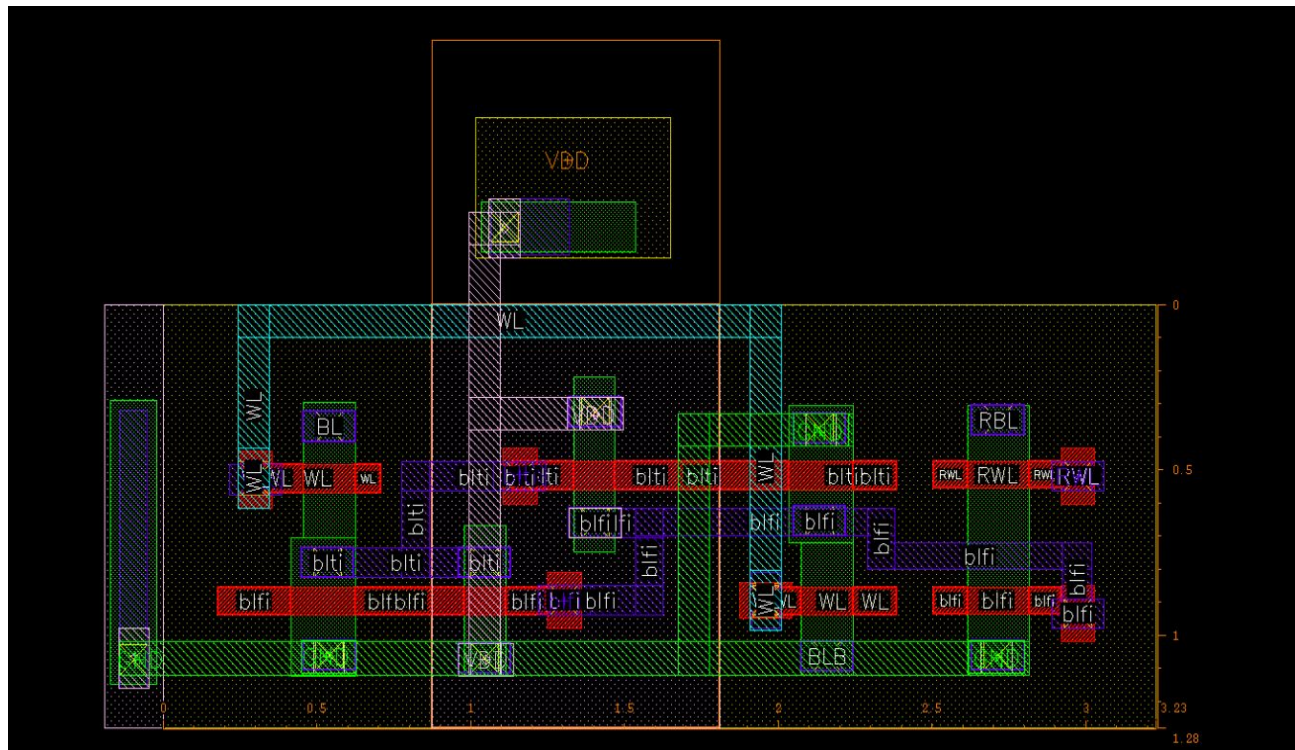
- In an scenario when,
 $Q = 1.08\text{ v}$ $Q' = 0\text{ v}$
(For MUX > 1)
- Ideally, RBL should not discharge, current should be zero when RWL gets high.
- However, due to a voltage bump (**blfi gets charged up**), both M7 and M8 experience a partial turn-on, represented by I_partial_on.

$I_{\text{Partial}}(\text{ON})$

1.08V

2.4008 μA

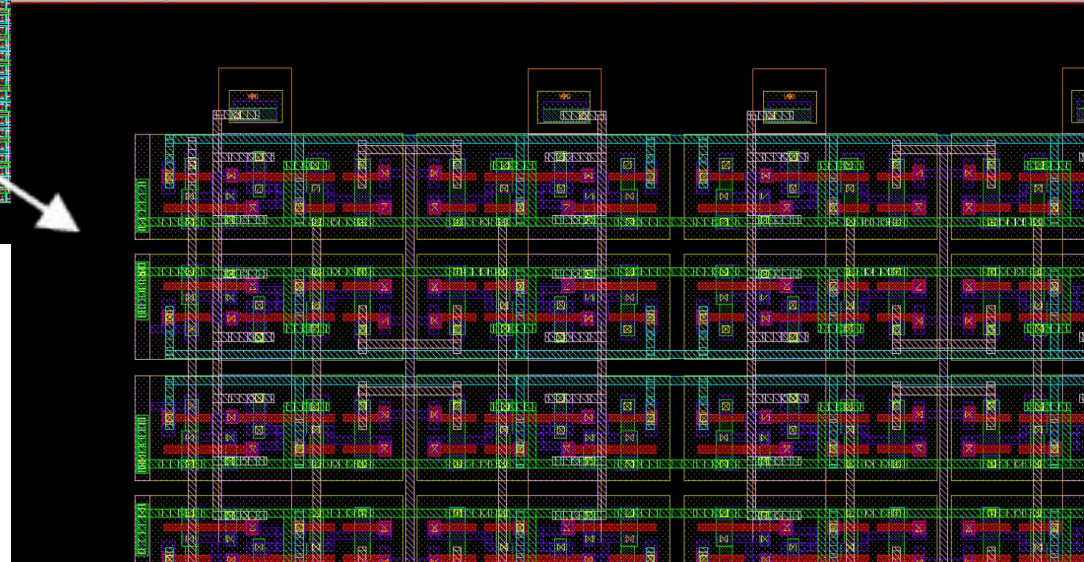
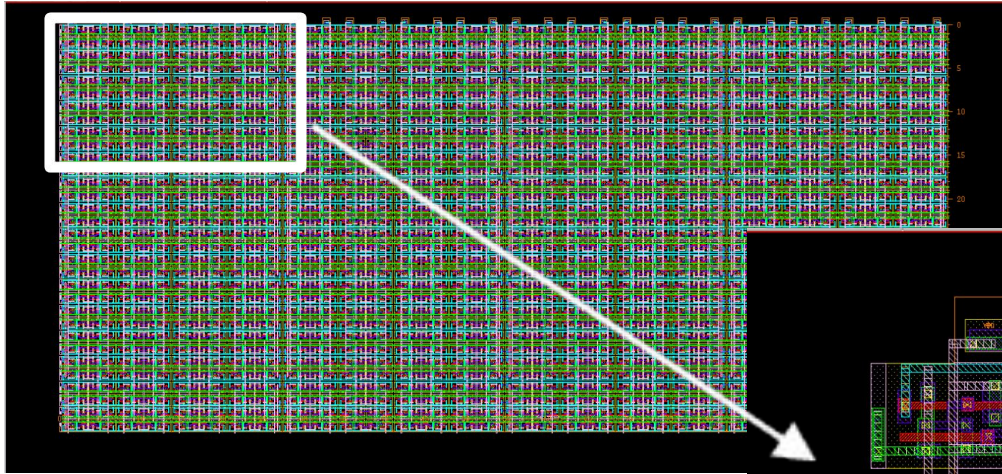
Layout



Bitcell Area:

$$1.28 \times 3.23 =$$
$$4.134 \mu\text{m}^2$$

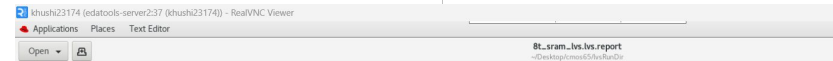
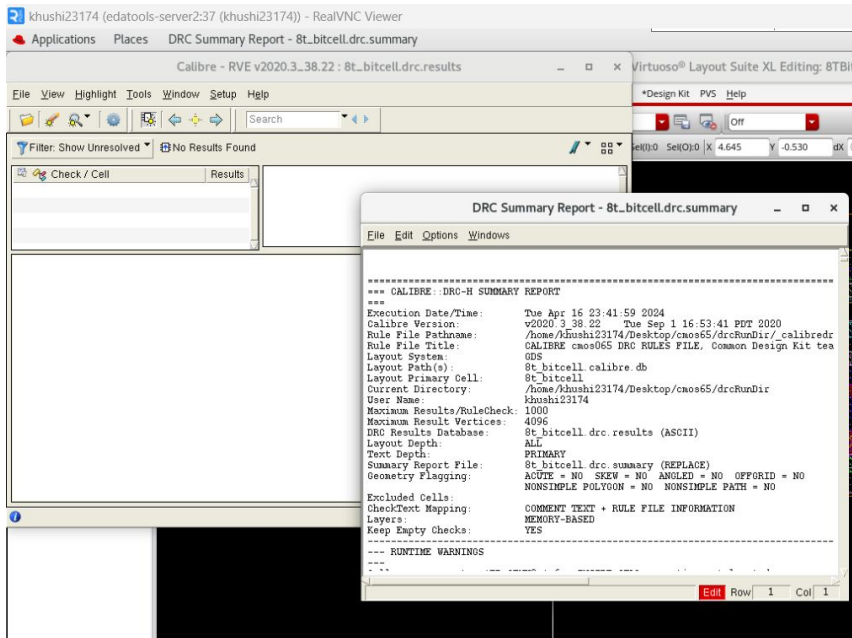
Layout of 32X32 Array



32x32 Array Area:

$$46.735 \times 109.175 =$$
$$5102.2936 \mu\text{m}^2$$

DRC and LVS clean Reports



```
==== CALIBRE SYSTEM ====
LVS REPORT
=====

REPORT FILE NAME: 8t_sram.lvs.lvs.report
LAYOUT NAME: /home/khushi23174/Desktop/cmos65/lvsRunDir/8t_sram.lvs.sp ('8t_sram.lvs')
SOURCE NAME: /home/khushi23174/Desktop/cmos65/lvsRunDir/8t_sram.lvs.src.net ('8t_sram.lvs')
RULE FILE: /home/khushi23174/Desktop/cmos65/lvsRunDir/_calibre_lvs.edited
RULE FILE TITLE: CALIBRE cmos65 LVS RULES FILE, Common technology kit team - Crolles, Date: Fri Mar 25 14:29:37 2011 $ - DPM rev L - CTK rev 5.3.6
CREATION TIME: Fri Apr 19 01:14:26 2024
CURRENT DIRECTORY: /home/khushi23174/Desktop/cmos65/lvsRunDir
USER NAME: khushi23174
CALIBRE VERSION: v2020.3_38.22 Tue Sep 1 16:53:41 PDT 2020
```

OVERALL COMPARISON RESULTS

```
#####
# # # CORRECT # #
# # #
```

CELL SUMMARY		
Result	Layout	Source
CORRECT	8t_sram_lvs	8t_sram_lvs
LVS PARAMETERS		

Conclusions and Future Plans:



◆ **Technical conclusions**

- ❖ Designed and analysed 8T sram cell, design specifications were met.
- ❖ Accomplished denser **32x32** SRAM cell array using technique of flipping and sharing.
- ❖ We successfully achieved custom layout design using Virtuoso, ensuring precise control over the placement and routing to meet minimum area constraint.

◆ **Emphasise on learning from the project**

- ❖ We were able to practically implement concepts related to SNM, statistics for VLSI and sram cell design.
- ❖ We utilize Virtuoso for schematic design and layout creation, ensuring LVS and DRC via Calibre.
- ❖ Post-layout parasitic extraction is performed using PEX.
- ❖ For evaluation FOMs and Monte Carlo simulations were done using Eldo and analyze waveforms with EZwave to validate and optimize our design for given specifications.
- ❖ Parasitic extraction degraded FOMs of cell to some extent.

◆ **Future plans**

- ❖ FOMs can be compared with different bitcells (viz. 6T, 8T 2R/W, 10T etc) for application specific analysis.
- ❖ Impact of parasitic extraction can be lowered by having performance oriented design approach.
- ❖ Performance improved 8T sram cell can be employed for IMC applications.

References



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- Simulations: "Eldo." Siemens EDA. [Online]. Available: <https://eda.sw.siemens.com/en-US/ic/eldo/>. [Accessed: March 10, 2024].
- Waveform Viewer: "EZwave." Siemens EDA. [Online]. Available: <https://www.eda-solutions.com/products/ezwave/>. [Accessed: March 10, 2024].

Work Distribution



Schematic Design, Layout and Array	Sizing and PVT Conditions	FOMs and Simulations
Khushi Kasbe, Vansh Singhai	Gangaprasad Horke, Khushi Kasbe	Vansh Singhai, Gangaprasad Horke